

WHAT IS CLAIMED IS:

1. A package for a rectangular integrated circuit,
comprising:

a frame type package, having a top portion, and a
bottom portion which defines at least one indented area
where a thickness between the top portion and the bottom
portion is thinner than in a non indented area, said
indented area sized to accept a rectangular integrated
circuit under a thinned portion of said indented area, and
said frame type package including a contact portion,
extending along at least said bottom portion and said
indented area, and adapted to connect to said rectangular
integrated circuit around an edge thereof.

2. A package as in claim 1, wherein said package
includes a connection portion, adapted for soldering to said
integrated circuit.

3. A package as in claim 2, wherein said integrated
circuit includes an image sensor, and a central portion of
said frame defines a portion where image light can enter
said image sensor.

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4. A package as in claim 1, further comprising an element which allows sealing said integrated circuit relative to the environment.
5. A package as in claim 3, further comprising a clear sealing element which allows sealing said integrated circuit relative to the environment.
6. A package as in claim 5, wherein said clear sealing element includes a glass lid.
7. A package as in claim 4, wherein said sealing element includes a lid portion on a top of the die and a backing portion on a rear portion of the die.
8. A package as in claim 7, wherein said indented area includes two separate sized indented areas, one sized to receive said die, and another sized to receive said backing portion.
9. A package as in claim 5, further comprising an element which protects said sealing element against damage.

10. A package as in claim 9, wherein said element which protects includes an extending part which extends above a top of said sealing element.

11. A package as in claim 3, further comprising an upper portion on said package, having surfaces adapted to accept a lens therein.

12. A package as in claim 11, wherein said surfaces include screw threads.

13. A package for an integrated circuit, comprising:
a packaging portion, having an outer perimeter with a
metal contact portion thereon, and an inner perimeter, said
inner perimeter formed by a downward facing surface with a
metal contact thereon, of a type which is adapted to connect
to an integrated circuit and a bottom and sideward facing
surface also having said metal contact portion thereon, said
contact portion extending from said outer perimeter to said
downward facing surface.

14. A package as in claim 13, further comprising an

element which seals an inside of said package as compared with an outside.

15. A package as in claim 14, wherein said element which seals is transparent.

16. A package as in claim 15, wherein said element is formed of glass, and is hermetically sealed around an area of said inner perimeter.

Mark 14 17. A package as in claim 16, further comprising a backing area, hermetically sealing a bottom portion, and wherein said metal contact travels around said bottom portion.

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